



RoHS Compliant



MDF1723

Single N-channel Trench MOSFET 40V, 85A, 2.6mΩ

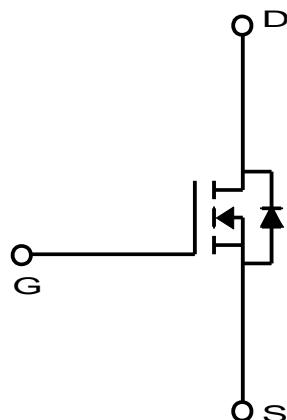
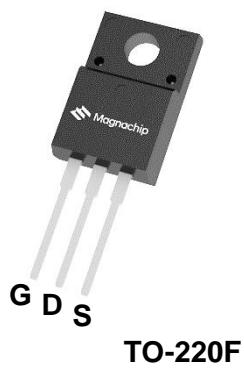
MDF1723- Single N-Channel Trench MOSFET 40V

General Description

The MDF1723 uses advanced Magnachip's MOSFET Technology, which provides high performance in on-state resistance, fast switching performance and excellent quality. MDF1723 is suitable device for Synchronous Rectification For Server and general purpose applications.

Features

- $V_{DS} = 40V$
- $I_D = 85A @ V_{GS} = 10V$
- $R_{DS(ON)} < 2.6 \text{ m}\Omega @ V_{GS} = 10V$
- 100% UIL Tested
- 100% R_g Tested



Absolute Maximum Ratings

Characteristics		Symbol	Rating	Unit
Drain-Source Voltage		V_{DSS}	40	V
Gate-Source Voltage		V_{GSS}	± 20	V
Continuous Drain Current ⁽¹⁾	$T_C=25^\circ\text{C}$ (Silicon Limited)	I_D	85.0	A
	$T_C=100^\circ\text{C}$		56.9	
Pulsed Drain Current		I_{DM}	340	
Power Dissipation	$T_C=25^\circ\text{C}$	P_D	34.8	W
	$T_C=100^\circ\text{C}$		13.9	
Single Pulse Avalanche Energy ⁽²⁾		E_{AS}	162.0	mJ
Junction and Storage Temperature Range		T_J, T_{stg}	-55~150	°C

Thermal Characteristics

Characteristics		Symbol	Rating	Unit
Thermal Resistance, Junction-to-Ambient ⁽¹⁾		$R_{\theta JA}$	62.5	°C/W
Thermal Resistance, Junction-to-Case		$R_{\theta JC}$	3.6	

Ordering Information

Part Number	Temp. Range	Package	Packing	RoHS Status
MDF1723TH	-55~150°C	TO-220F	Tube	Halogen Free

Electrical Characteristics ($T_J = 25^\circ\text{C}$ unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Typ	Max	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$I_D = 250\mu\text{A}, V_{\text{GS}} = 0\text{V}$	40	-	-	V
Gate Threshold Voltage	$V_{\text{GS(th)}}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	2.0	-	4.0	
Drain Cut-Off Current	I_{DSS}	$V_{\text{DS}} = 32\text{V}, V_{\text{GS}} = 0\text{V}$	-	-	1.0	μA
Gate Leakage Current	I_{GSS}	$V_{\text{GS}} = \pm 20\text{V}, V_{\text{DS}} = 0\text{V}$	-	-	± 0.1	
Drain-Source ON Resistance	$R_{\text{DS(ON)}}$	$V_{\text{GS}} = 10\text{V}, I_D = 40\text{A}$	-	2.2	2.6	$\text{m}\Omega$
Forward Transconductance	g_{fs}	$V_{\text{DS}} = 10\text{V}, I_D = 40\text{A}$	-	111	-	S
Dynamic Characteristics						
Total Gate Charge	Q_g	$V_{\text{DS}} = 20\text{V}, I_D = 40\text{A}, V_{\text{GS}} = 10\text{V}$	-	88.3	-	nC
Gate-Source Charge	Q_{gs}		-	22.9	-	
Gate-Drain Charge	Q_{gd}		-	16.5	-	
Input Capacitance	C_{iss}	$V_{\text{DS}} = 20\text{V}, V_{\text{GS}} = 0\text{V}, f = 1.0\text{MHz}$	-	5755	-	pF
Reverse Transfer Capacitance	C_{rss}		-	203	-	
Output Capacitance	C_{oss}		-	1830	-	
Turn-On Delay Time	$t_{\text{d(on)}}$	$V_{\text{GS}} = 10\text{V}, V_{\text{DS}} = 20\text{V}, I_D = 40\text{A}, R_G = 3.0\Omega$	-	24.3	-	ns
Rise Time	t_r		-	14.7	-	
Turn-Off Delay Time	$t_{\text{d(off)}}$		-	84.8	-	
Fall Time	t_f		-	42.7	-	
Gate Resistance	R_g	$f=1\text{ MHz}$	-	3.0	-	Ω
Drain-Source Body Diode Characteristics						
Source-Drain Diode Forward Voltage	V_{SD}	$I_S = 40\text{A}, V_{\text{GS}} = 0\text{V}$	-	0.9	1.2	V
Body Diode Reverse Recovery Time	t_{rr}	$I_F = 40\text{A}, dI/dt = 100\text{A}/\mu\text{s}$	-	55.7	-	ns
Body Diode Reverse Recovery Charge	Q_{rr}		-	82.0	-	nC

Note :

1. Surface mounted FR-4 board by JEDEC (jesd51-7). Continuous current at $T_c=25^\circ\text{C}$ is silicon limited
2. E_{AS} is tested at starting $T_J = 25^\circ\text{C}$, $L = 1.0\text{mH}$, $I_{\text{AS}} = 18.0\text{A}$, $V_{\text{GS}} = 10\text{V}$.

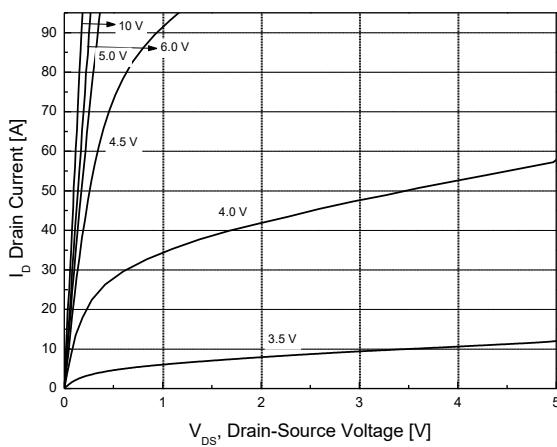


Fig.1 On-Region Characteristics

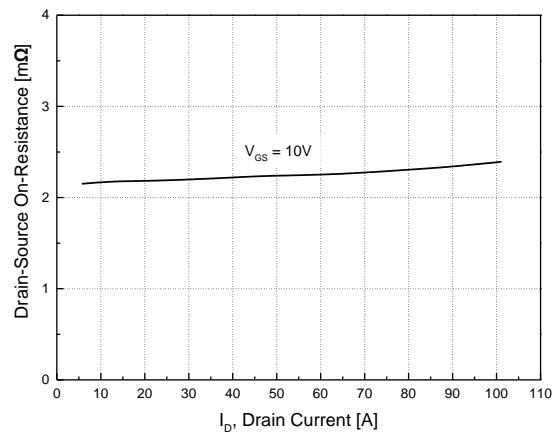


Fig.2 On-Resistance Variation with Drain Current and Gate Voltage

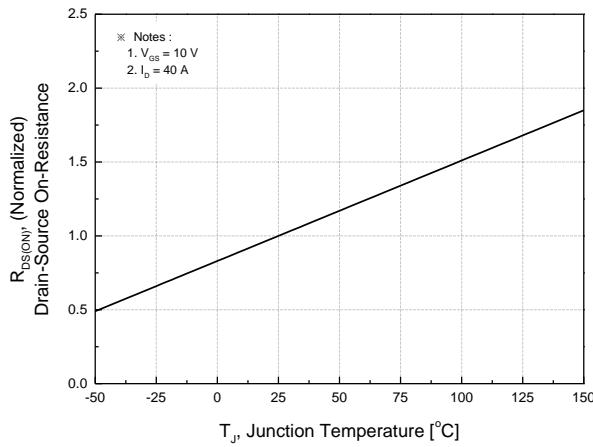


Fig.3 On-Resistance Variation with Temperature

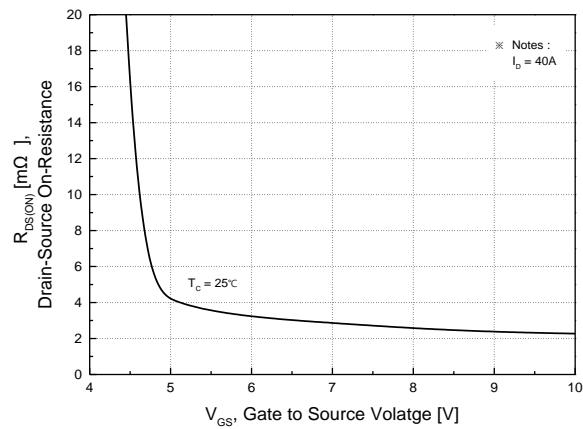


Fig.4 On-Resistance Variation with Gate to Source Voltage

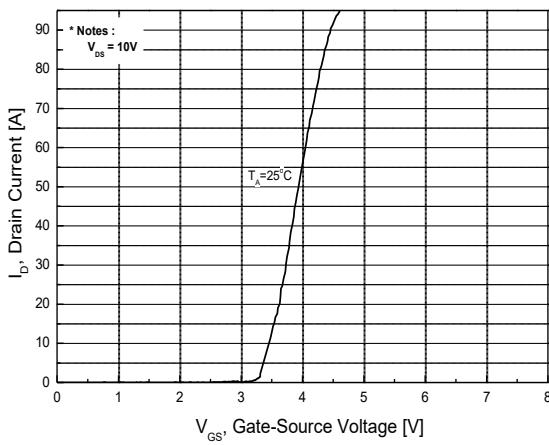


Fig.5 Transfer Characteristics

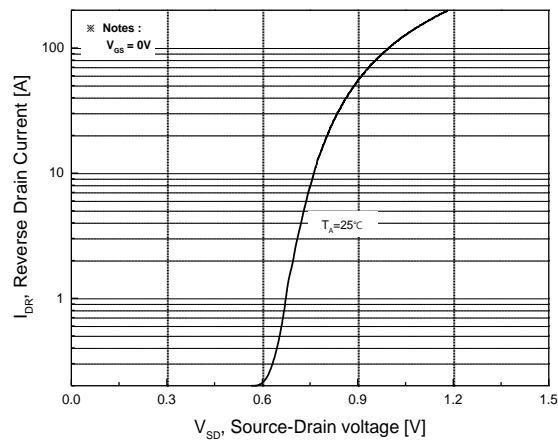


Fig.6 Body Diode Forward Voltage Variation with Source Current and Temperature

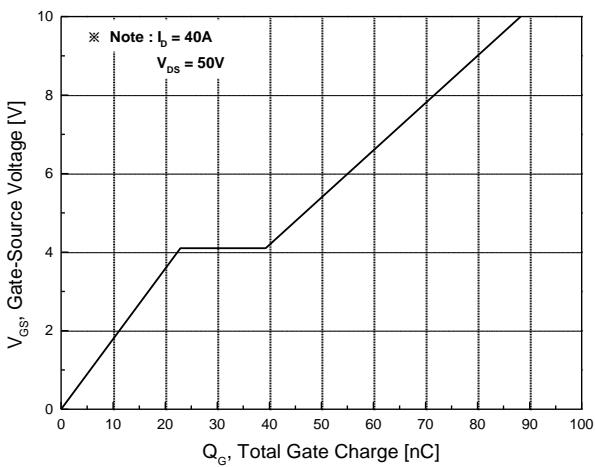


Fig.7 Gate Charge Characteristics

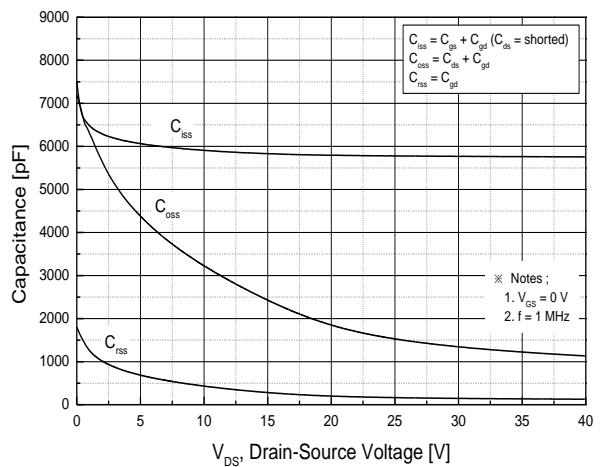


Fig.8 Capacitance Characteristics

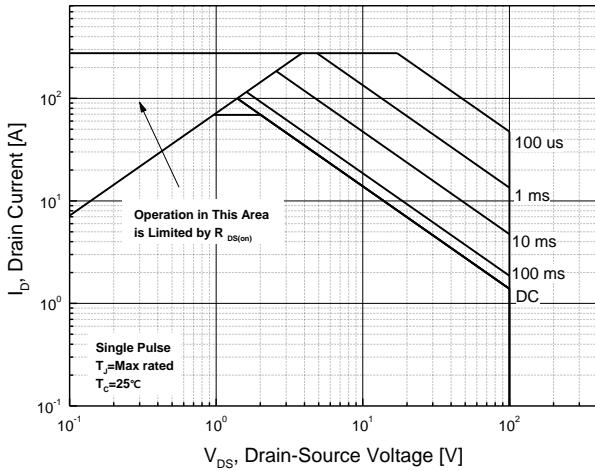


Fig.9 Maximum Safe Operating Area

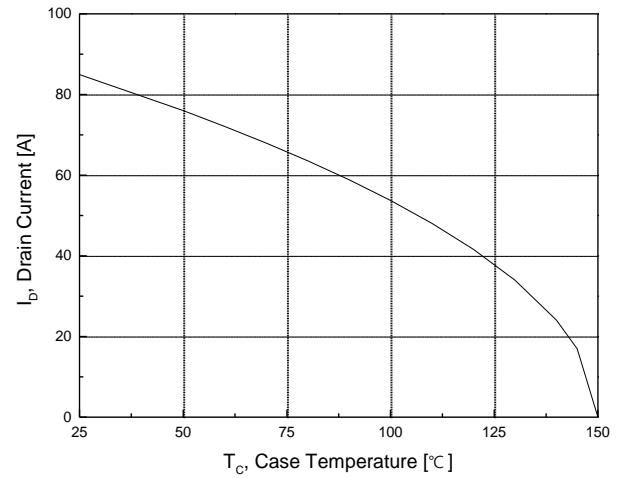


Fig.10 Maximum Drain Current vs. Case Temperature

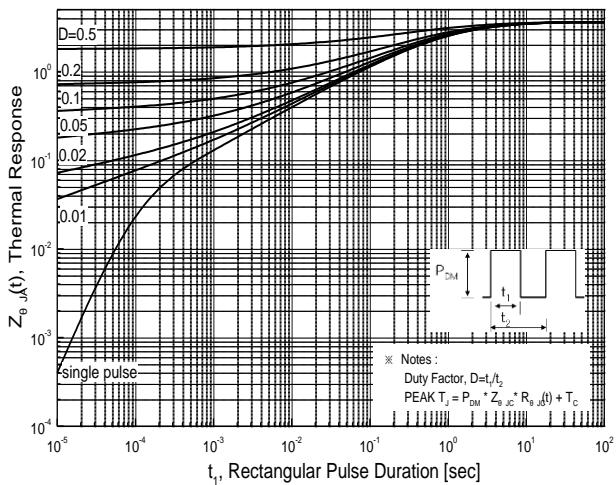
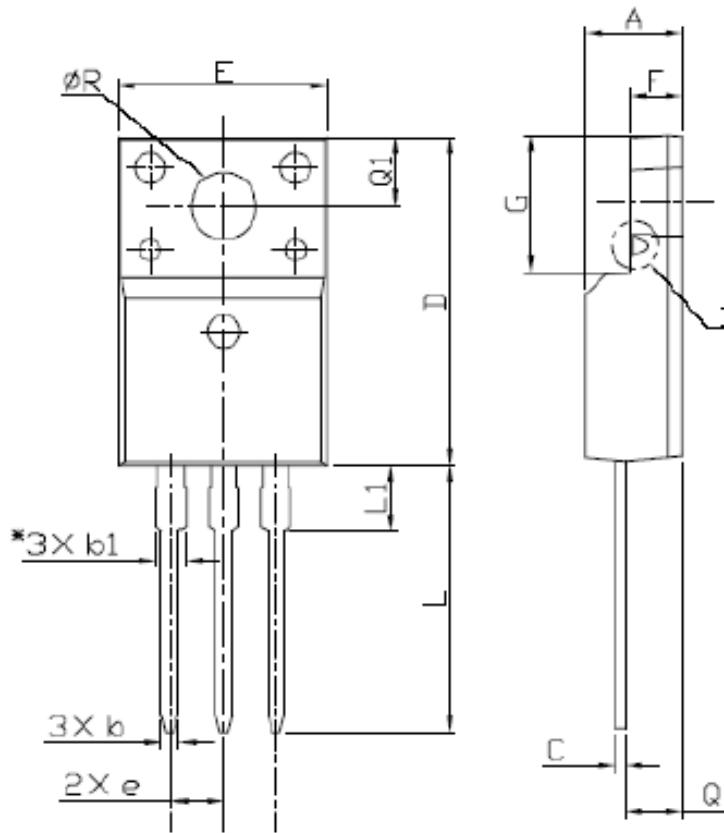


Fig.11 Transient Thermal Response Curve

Package Dimension

TO-220F

Dimensions are in millimeters unless otherwise specified



Symbol	Min	Nom	Max
A	4.50	-	4.93
b	0.63	-	0.91
b1	1.15	-	1.47
C	0.33	-	0.63
D	15.47	-	16.13
E	9.60	-	10.71
e	2.54 BSC		
F	2.34	-	2.84
G	6.48	-	6.90
L	12.24	-	13.72
L1	2.79	-	3.67
Q	2.52	-	2.96
Q1	3.10	-	3.50
ØR	3.00	-	3.55

Note : Package body size, length and width do not include mold flash, protrusions and gate burrs.

DISCLAIMER:

The Products are not designed for use in hostile environments, including, without limitation, aircraft, nuclear power generation, medical appliances, and devices or systems in which malfunction of any Product can reasonably be expected to result in a personal injury. Seller's customers using or selling Seller's products for use in such applications do so at their own risk and agree to fully defend and indemnify Seller.

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